

	Hit s	Search Text	DBs
21	34	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern or vias)) and ((metal\$4 or conductive or Sn or Pd or Cu or copper or tin or palladium) same (immers\$4 or dip\$4 or suspension) same (selective\$3 near28 (region or site or area or portion or exposed or surface)) same (ITO or (indium near9 tin near9 oxide)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
22	0	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide)) and ((metal\$4 or conductive or Sn or Pd or Cu or copper or tin or palladium) same (immers\$4 or dip\$4 or suspension or solution) same (nuclei or nucleat\$4 or catalys\$4 or catalytic\$4) same (ITO or (indium near9 tin near9 oxide)) same selective\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
23	3	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide)) and ((metal\$4 or conductive or Sn or Pd or Cu or copper or tin or palladium) same (immers\$4 or dip\$4 or suspension or solution) same (nuclei or nucleat\$4 or catalys\$4 or catalytic\$4) same selective\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
24	10	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide)) and ((metal\$4 or conductive or Sn or Pd or Cu or copper or tin or palladium) same (immers\$4 or dip\$4 or suspension or solution) same (nuclei or nucleat\$4 or catalys\$4 or catalytic\$4))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
25	2	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide)) and ((catalytic or catalyst) near6 (ions or solution or suspension) near24 (palladium or Pd)) and (electroless near4 plat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
26	3	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide)) and ((catalytic or catalyst) near24 (palladium or Pd)) and (electroless near4 plat\$4)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hit s	Search Text	DBs
27	219	((substrate or wafer or device or platen or surface) same (mask\$4 or pattern) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (acrylate or polycarbonate or polyimide))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
28	390	(substrate or wafer or device or platen or surface) near16 (ITO or (indium near4 tin near4 oxide) same (mask or pattern) same (resist or photoresist)) and ((metal\$4 or conductive or Sn or Pd or Cu or copper or tin or palladium) same (selective\$3 near28 (region or site or area or portion or exposed or portion)) same (ITO or (indium near9 tin near9 oxide)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB